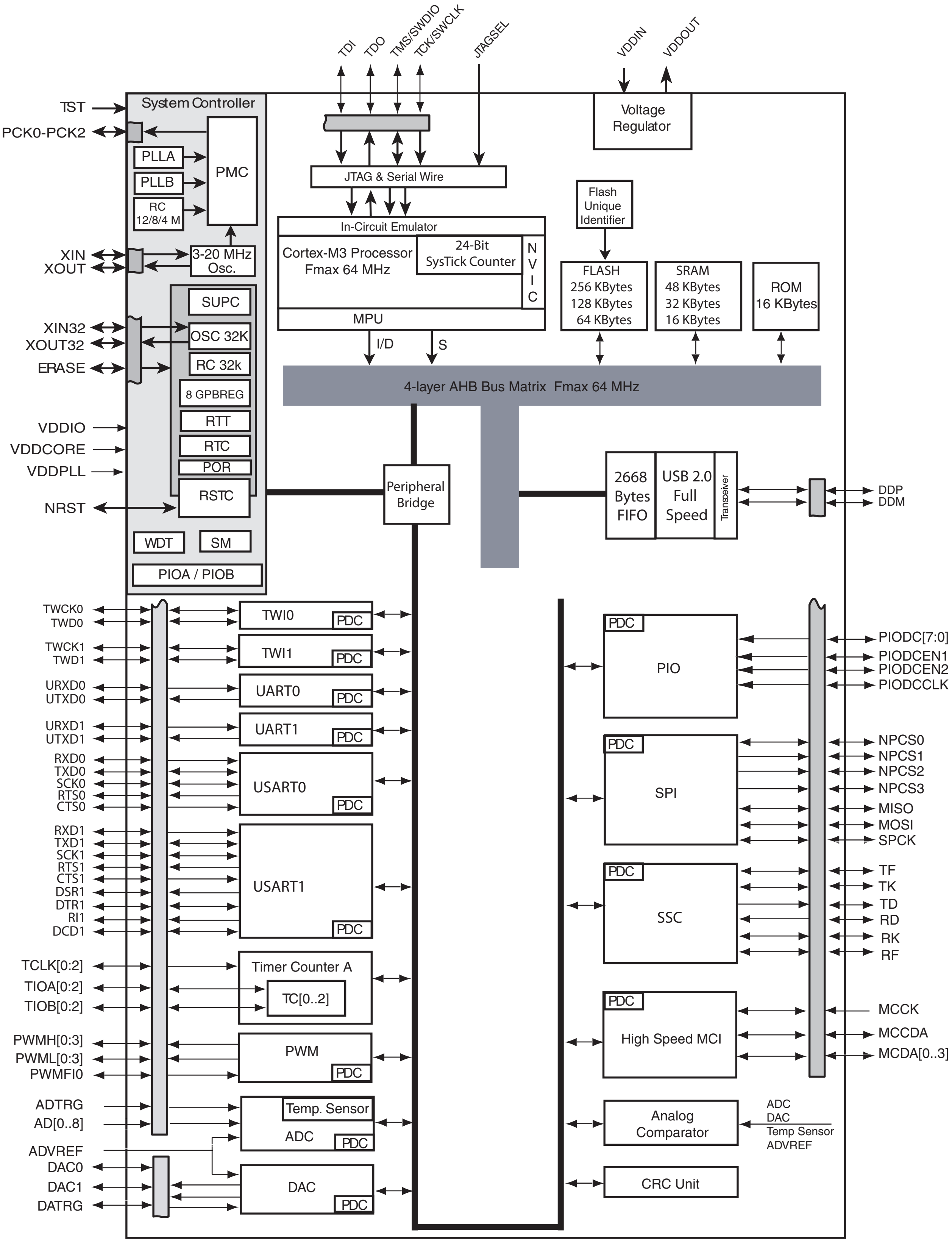
Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	I²C, MMC, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	47
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x10/12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/atsam3s1ba-mu

Figure 2-2. SAM3S 64-pin Version Block Diagram



4.1.4 100-ball LFBGA Pinout

Table 4-2. 100-ball LFBGA SAM3S4/2/1C Pinout

A1	PB1/AD5
A2	PC29
A3	VDDIO
A4	PB9/PGMCK/XIN
A5	PB8/XOUT
A6	PB13/DAC0
A7	DDP/PB11
A8	DDM/PB10
A9	TMS/SWDIO/PB6
A10	JTAGSEL
B1	PC30
B2	ADVREF
B3	GNDANA
B4	PB14/DAC1
B5	PC21
B6	PC20
B7	PA31
B8	PC19
B9	PC18
B10	TDO/TRACESWO/ PB5
C1	PB2/AD6
C2	VDDPLL
C3	PC25
C4	PC23
C5	ERASE/PB12

C6	TCK/SWCLK/PB7
C7	PC16
C8	PA1/PGMEN1
C9	PC17
C10	PA0/PGMEN0
D1	PB3/AD7
D2	PB0/AD4
D3	PC24
D4	PC22
D5	GND
D6	GND
D7	VDDCORE
D8	PA2/PGMEN2
D9	PC11
D10	PC14
E1	PA17/PGMD5/AD0
E2	PC31
E3	VDDIN
E4	GND
E5	GND
E6	NRST
E7	PA29/AD13
E8	PA30/AD14
E9	PC10
E10	PA3

F1	PA18/PGMD6/AD1
F2	PC26
F3	VDDOUT
F4	GND
F5	VDDIO
F6	PA27/PGMD15
F7	PC8
F8	PA28
F9	TST
F10	PC9
G1	PA21/PGMD9/AD8
G2	PC27
G3	PA15/PGMD3
G4	VDDCORE
G5	VDDCORE
G6	PA26/PGMD14
G7	PA12/PGMD0
G8	PC28
G9	PA4/PGMNCMD
G10	PA5/PGMRDY
H1	PA19/PGMD7/AD2
H2	PA23/PGMD11
H3	PC7
H4	PA14/PGMD2
H5	PA13/PGMD1

H6	PC4
H7	PA11/PGMM3
H8	PC1
H9	PA6/PGMNOE
H10	TDI/PB4
J1	PC15/AD11
J2	PC0
J3	PA16/PGMD4
J4	PC6
J5	PA24/PGMD12
J6	PA25/PGMD13
J7	PA10/PGMM2
J8	GND
J9	VDDCORE
J10	VDDIO
K1	PA22/PGMD10/AD9
K2	PC13/AD10
K3	PC12/AD12
K4	PA20/PGMD8/AD3
K5	PC5
K6	PC3
K7	PC2
K8	PA9/PGMM1
K9	PA8/XOUT32/PGMM0
K10	PA7/XIN32/ PGMNVALID

5. Power Considerations

5.1 Power Supplies

The SAM3S product has several types of power supply pins:

- VDDCORE pins: Power the core, the embedded memories and the peripherals; voltage ranges from 1.62V and 1.95V.
- VDDIO pins: Power the Peripherals I/O lines (Input/Output Buffers); USB transceiver; Backup part, 32kHz crystal oscillator and oscillator pads; ranges from 1.62V and 3.6V
- VDDIN pin: Voltage Regulator Input, ADC, DAC and Analog Comparator Power Supply; Voltage ranges from 1.8V to 3.6V
- VDDPLL pin: Powers the PLLA, PLLB, the Fast RC and the 3 to 20 MHz oscillator; voltage ranges from 1.62V and 1.95V.

5.2 Voltage Regulator

The SAM3S embeds a voltage regulator that is managed by the Supply Controller.

This internal regulator is intended to supply the internal core of SAM3S. It features two different operating modes:

- In Normal mode, the voltage regulator consumes less than 700 µA static current and draws 80 mA of output current. Internal adaptive biasing adjusts the regulator quiescent current depending on the required load current. In Wait Mode quiescent current is only 7 µA.

• In Backup mode, the voltage regulator consumes less than 1 µA while its output (VDDOUT) is driven internally to GND. The default output voltage is 1.80V and the start-up time to reach Normal mode is inferior to 100 µs.

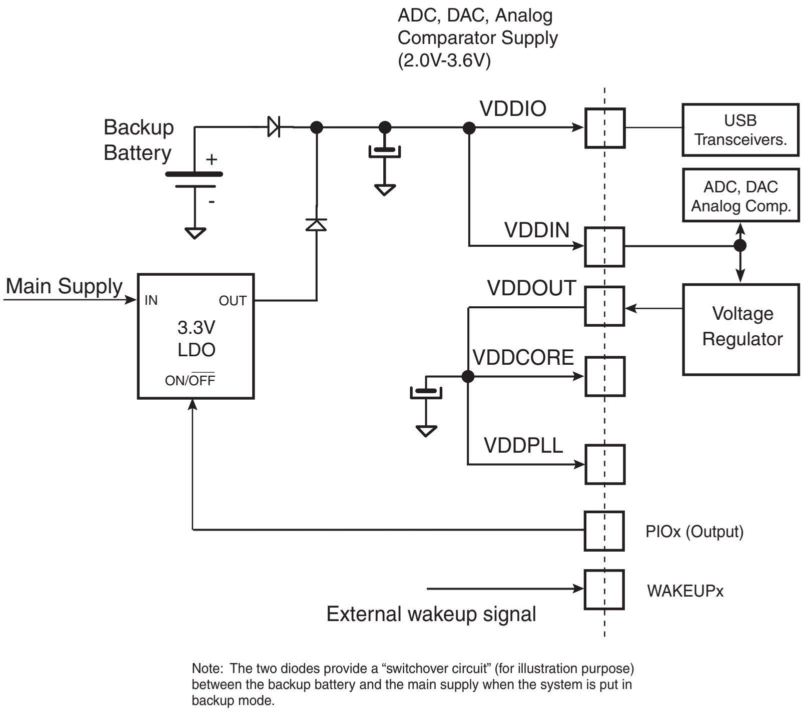
For adequate input and output power supply decoupling/bypassing, refer to the Voltage Regulator section in the Electrical Characteristics section of the datasheet.

5.3 Typical Powering Schematics

The SAM3S supports a 1.62V-3.6V single supply mode. The internal regulator input connected to the source and its output feeds VDDCORE. Figure 5-1 shows the power schematics.

As VDDIN powers the voltage regulator, the ADC/DAC and the analog comparator, when the user does not want to use the embedded voltage regulator, it can be disabled by software via the SUPC (note that it is different from Backup mode).

Figure 5-3. Backup Battery



Note: The two diodes provide a "switchover circuit" (for illustration purpose) between the backup battery and the main supply when the system is put in backup mode.

5.4 Active Mode

Active mode is the normal running mode with the core clock running from the fast RC oscillator, the main crystal oscillator or the PLLA. The power management controller can be used to adapt the frequency and to disable the peripheral clocks.

5.5 Low Power Modes

The various low power modes of the SAM3S are described below:

5.5.1 Backup Mode

The purpose of backup mode is to achieve the lowest power consumption possible in a system which is performing periodic wake-ups to perform tasks but not requiring fast startup time (<0.1ms). Total current consumption is 3 µA typical.

The Supply Controller, zero-power power-on reset, RTT, RTC, Backup registers and 32 kHz oscillator (RC or crystal oscillator selected by software in the Supply Controller) are running. The regulator and the core supply are off.

Backup mode is based on the Cortex-M3 deepsleep mode with the voltage regulator disabled.

The SAM3S can be awakened from this mode through WUP0-15 pins, the supply monitor (SM), the RTT or RTC wake-up event.

Backup mode is entered by using WFE instructions with the SLEEPDEEP bit in the System Control Register of the Cortex-M3 set to 1. (See the Power management description in The ARM Cortex M3 Processor section of the product datasheet).

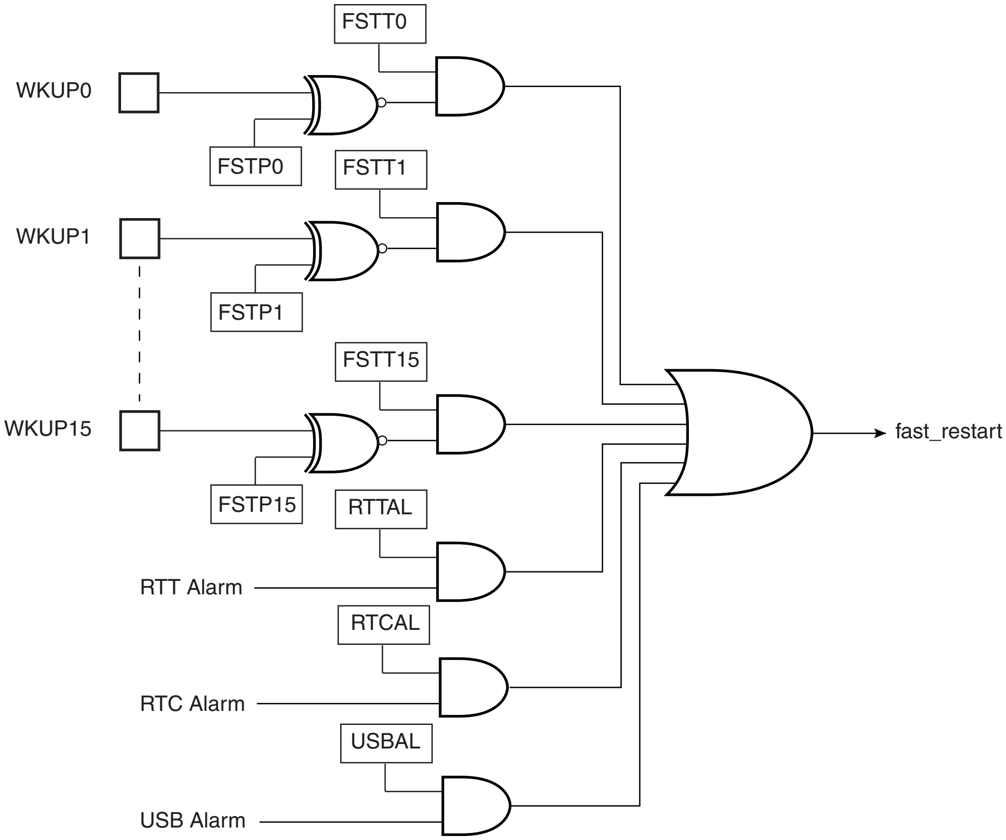
Exit from Backup mode happens if one of the following enable wake up events occurs:

5.7 Fast Startup

The device allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in Figure 5-5, is fully asynchronous and provides a fast start-up signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4/8/12 MHz fast RC oscillator, switches the master clock on this 4MHz clock and reenables the processor clock.

Figure 5-5. Fast Start-Up Circuitry



6. Input/Output Lines

The SAM3S has several kinds of input/output (I/O) lines such as general purpose I/Os (GPIO) and system I/Os. GPIOs can have alternate functionality due to multiplexing capabilities of the PIO controllers. The same PIO line can be used whether in IO mode or by the multiplexed peripheral. System I/Os include pins such as test pins, oscillators, erase or analog inputs.

6.1 General Purpose I/O Lines

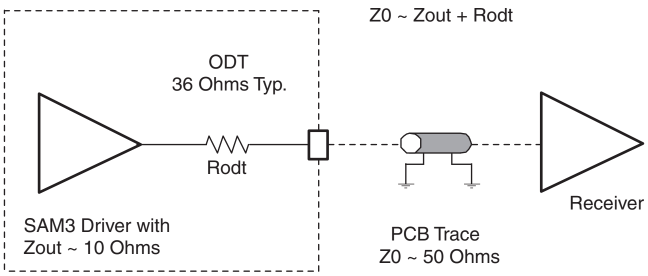
GPIO Lines are managed by PIO Controllers. All I/Os have several input or output modes such as pull-up or pull-down, input Schmitt triggers, multi-drive (open-drain), glitch filters, debouncing or input change interrupt. Programming of these modes is performed independently for each I/O line through the PIO controller user interface. For more details, refer to the product PIO controller section.

The input output buffers of the PIO lines are supplied through VDDIO power supply rail.

The SAM3S embeds high speed pads able to handle up to 32 MHz for HSMCI (MCK/2), 45 MHz for SPI clock lines and 35 MHz on other lines. See AC Characteristics Section in the Electrical Characteristics Section of the datasheet for more details. Typical pull-up and pull-down value is 100 kΩ for all I/Os.

Each I/O line also embeds an ODT (On-Die Termination), see Figure 6-1. It consists of an internal series resistor termination scheme for impedance matching between the driver output (SAM3S) and the PCB trace impedance preventing signal reflection. The series resistor helps to reduce IOs switching current (di/dt) thereby reducing in turn, EMI. It also decreases overshoot and undershoot (ringing) due to inductance of interconnect between devices or between boards. In conclusion ODT helps diminish signal integrity issues.

Figure 6-1. On-Die Termination



6.2 System I/O Lines

System I/O lines are pins used by oscillators, test mode, reset and JTAG to name but a few. Described below are the SAM3S system I/O lines shared with PIO lines:

These pins are software configurable as general purpose I/O or system pins. At startup the default function of these pins is always used.

7.5 Master to Slave Access

All the Masters can normally access all the Slaves. However, some paths do not make sense, for example allowing access from the Cortex-M3 S Bus to the Internal ROM. Thus, these paths are forbidden or simply not wired and shown as "-" in the following table.

Table 7-3. SAM3S Master to Slave Access

	Masters	**0**	**1**	**2**	**3**
Slaves		Cortex-M3 I/D Bus	Cortex-M3 S Bus	PDC	CRCCU
0	Internal SRAM	-	X	X	X
1	Internal ROM	X	-	X	X
2	Internal Flash	X	-	-	X
3	External Bus Interface	-	X	X	X
4	Peripheral Bridge	-	X	X	-

7.6 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirement

The Peripheral DMA Controller handles transfer requests from the channel according to the following priorities (Low to High priorities):

Table 7-4. Peripheral DMA Controller

Instance Name	Channel T/R	100 & 64 Pins	48 Pins
PWM	Transmit	x	x
TWI1	Transmit	x	x
TWI0	Transmit	x	x
UART1	Transmit	x	x
UART0	Transmit	x	x
USART1	Transmit	x	N/A
USART0	Transmit	x	x
DAC	Transmit	x	N/A
SPI	Transmit	x	x
SSC	Transmit	x	x
HSMCI	Transmit	x	N/A
PIOA	Transmit	x	x
TWI1	Receive	x	x
TWI0	Receive	x	x
UART1	Receive	x	N/A

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The ATSAM3S4 product (256-Kbyte internal Flash version) embeds a total of 48 Kbytes high-speed SRAM.

The ATSAM3S2 product (128-Kbyte internal Flash version) embeds a total of 32 Kbytes high-speed SRAM.

The ATSAM3S1 product (64-Kbyte internal Flash version) embeds a total of 16 Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is mapped from 0x2200 0000 to 0x23FF FFFF.

9.1.2 Internal ROM

The SAM3S product embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the ATSAM3S4 (256-Kbytes internal Flash version) is organized in one bank of 1024 pages (Single plane) of 256 bytes.

The Flash of the ATSAM3S2 (128-Kbytes internal Flash version) is organized in one bank of 512 pages (Single plane) of 256 bytes.

The Flash of the ATSAM3S1 (64-Kbytes internal Flash version) is organized in one bank of 256 pages (Single plane) of 256 bytes.

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32-bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

  - Asynchronous read in Page Mode supported (4- up to 32-byte page size)
- Multiple device adaptability
  - Control signals programmable setup, pulse and hold time for each Memory Bank
- Multiple Wait State Management
  - Programmable Wait State Generation
  - External Wait Request
  - Programmable Data Float Time
- Slow Clock mode supported
- Additional Logic for NAND Flash

10.1 System Controller and Peripherals Mapping

Please refer to Section 8-1 "SAM3S Product Mapping" on page 30.

All the peripherals are in the bit band region and are mapped in the bit band alias region.

10.2 Power-on-Reset, Brownout and Supply Monitor

The SAM3S embeds three features to monitor, warn and/or reset the chip:

- Power-on-Reset on VDDIO
- Brownout Detector on VDDCORE
- Supply Monitor on VDDIO

10.2.1 Power-on-Reset

The Power-on-Reset monitors VDDIO. It is always activated and monitors voltage at start up but also during power down. If VDDIO goes below the threshold voltage, the entire chip is reset. For more information, refer to the Electrical Characteristics section of the datasheet.

10.2.2 Brownout Detector on VDDCORE

The Brownout Detector monitors VDDCORE. It is active by default. It can be deactivated by software through the Supply Controller (SUPC_MR). It is especially recommended to disable it during low-power modes such as wait or sleep modes.

If VDDCORE goes below the threshold voltage, the reset of the core is asserted. For more information, refer to the Supply Controller (SUPC) and Electrical Characteristics sections of the datasheet.

10.2.3 Supply Monitor on VDDIO

The Supply Monitor monitors VDDIO. It is not active by default. It can be activated by software and is fully programmable with 16 steps for the threshold (between 1.9V to 3.4V). It is controlled by the Supply Controller (SUPC). A sample mode is possible. It allows to divide the supply monitor power consumption by a factor of up to 2048. For more information, refer to the SUPC and Electrical Characteristics sections of the datasheet.

10.3 Reset Controller

The Reset Controller is based on a Power-on-Reset cell, and a Supply Monitor on VDDCORE.

The Reset Controller is capable to return to the software the source of the last reset, either a general reset, a wake-up reset, a software reset, a user reset or a watchdog reset.

The Reset Controller controls the internal resets of the system and the NRST pin input/output. It is capable to shape a reset signal for the external devices, simplifying to a minimum connection of a push-button on the NRST pin to implement a manual reset.

The configuration of the Reset Controller is saved as supplied on VDDIO.

10.4 Supply Controller (SUPC)

The Supply Controller controls the power supplies of each section of the processor and the peripherals (via Voltage regulator control)

The Supply Controller has its own reset circuitry and is clocked by the 32 kHz Slow clock generator.

- Alarm register capable to generate a wake-up of the system through the Shut Down Controller

10.10 Real Time Clock

- Low power consumption
- Full asynchronous design
- Two hundred year calendar
- Programmable Periodic Interrupt
- Alarm and update parallel load
- Control of alarm and update Time/Calendar Data In

10.11 General Purpose Backup Registers

- Eight 32-bit general-purpose backup registers

10.12 Nested Vectored Interrupt Controller

- Thirty maskable external interrupts
- Sixteen priority levels
- Processor state automatically saved on interrupt entry, and restored on
- Dynamic reprioritization of interrupts
- Priority grouping.
  - selection of preempting interrupt levels and non-preempting interrupt levels.
- Support for tail-chaining and late arrival of interrupts.
  - back-to-back interrupt processing without the overhead of state saving and restoration between interrupts.
- Processor state automatically saved on interrupt entry, and restored on interrupt exit, with no instruction overhead.

10.13 Chip Identification

- Chip Identifier (CHIPID) registers permit recognition of the device and its revision.

Table 10-1. SAM3S Chip IDs Register

Chip Name	Flash Size (KBytes)	Pin Count	DBGU_CIDR	CHIPID_EXID
ATSAM3S4A (Rev A)	256	48	0x28800960	0x0
ATSAM3S2A (Rev A)	128	48	0x288A0760	0x0
ATSAM3S1A (Rev A)	64	48	0x28890560	0x0
ATSAM3S4B (Rev A)	256	64	0x28900960	0x0
ATSAM3S2B (Rev A)	128	64	0x289A0760	0x0
ATSAM3S1B (Rev A)	64	64	0x28990560	0x0
ATSAM3S4C (Rev A)	256	100	0x28A00960	0x0
ATSAM3S2C (Rev A)	128	100	0x28AA0760	0x0
ATSAM3S1C (Rev A)	64	100	0x28A90560	0x0

- JTAG ID: 0x05B2D03F

11.2.2 PIO Controller B Multiplexing

Table 11-3. Multiplexing on PIO Controller B (PIOB)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PB0	PWMH0			AD4		
PB1	PWMH1			AD5		
PB2	URXD1	NPCS2		AD6/ WKUP12		
PB3	UTXD1	PCK2		AD7		
PB4	TWD1	PWMH2			TDI	
PB5	TWCK1	PWML0		WKUP13	TDO/TRACESWO	
PB6					TMS/SWDIO	
PB7					TCK/SWCLK	
PB8					XOUT	
PB9					XIN	
PB10					DDM	
PB11					DDP	
PB12	PWML1				ERASE	
PB13	PWML2	PCK0		DAC0		64/100-pin versions
PB14	NPCS1	PWMH3		DAC1		64/100-pin versions

  - Interval Measurement
  - Pulse Generation
  - Delay Timing
  - Pulse Width Modulation
  - Up/down Capabilities
- Each channel is user-configurable and contains:
  - Three external clock inputs
  - Five internal clock inputs
  - Two multi-purpose input/output signals
- Two global registers that act on all three TC Channels
- Quadrature decoder
  - Advanced line filtering
  - Position / revolution / speed
- 2-bit Gray Up/Down Counter for Stepper Motor

12.7 Pulse Width Modulation Controller (PWM)

- One Four-channel 16-bit PWM Controller, 16-bit counter per channel
- Common clock generator, providing Thirteen Different Clocks
  - A Modulo n counter providing eleven clocks
  - Two independent Linear Dividers working on modulo n counter outputs
  - High Frequency Asynchronous clocking mode
- Independent channel programming
  - Independent Enable Disable Commands
  - Independent Clock Selection
  - Independent Period and Duty Cycle, with Double Buffering
  - Programmable selection of the output waveform polarity
  - Programmable center or left aligned output waveform
  - Independent Output Override for each channel
  - Independent complementary Outputs with 12-bit dead time generator for each channel
  - Independent Enable Disable Commands
  - Independent Clock Selection
  - Independent Period and Duty Cycle, with Double Buffering
- Synchronous Channel mode
  - Synchronous Channels share the same counter
  - Mode to update the synchronous channels registers after a programmable number of periods
- Connection to one PDC channel
  - Offers Buffer transfer without Processor Intervention, to update duty cycle of synchronous channels
- independent event lines which can send up to 4 triggers on ADC within a period

- Programmable gain: 1, 2, 4

12.11 Digital-to-Analog Converter (DAC)

- Up to 2 channel 12-bit DAC
- Up to 2 mega-samples conversion rate in single channel mode
- Flexible conversion range
- Multiple trigger sources for each channel
- 2 Sample/Hold (S/H) outputs
- Built-in offset and gain calibration
- Possibility to drive output to ground
- Possibility to use as input to analog comparator or ADC (as an internal wire and without S/H stage)
- Two PDC channels
- Power reduction mode

12.12 Static Memory Controller

- 16-Mbyte Address Space per Chip Select
- 8- bit Data Bus
- Word, Halfword, Byte Transfers
- Programmable Setup, Pulse And Hold Time for Read Signals per Chip Select
- Programmable Setup, Pulse And Hold Time for Write Signals per Chip Select
- Programmable Data Float Time per Chip Select
- External Wait Request
- Automatic Switch to Slow Clock Mode
- Asynchronous Read in Page Mode Supported: Page Size Ranges from 4 to 32 Bytes
- NAND FLASH additional logic supporting NAND Flash with Multiplexed Data/Address buses
- Hardware Configurable number of chip select from 1 to 4
- Programmable timing on a per chip select basis

12.13 Analog Comparator

- One analog comparator
- High speed option vs. low power option
- Selectable input hysteresis:
  - 0, 20 mV, 50 mV
- Minus input selection:
  - DAC outputs
  - Temperature Sensor
  - ADVREF
  - AD0 to AD3 ADC channels
- Plus input selection:
  - All analog inputs

- output selection:
  - Internal signal
  - external pin
  - selectable inverter
- Interrupt on:
  - Rising edge, Falling edge, toggle

12.14 Cyclic Redundancy Check Calculation Unit (CRCCU)

- 32-bit cyclic redundancy check automatic calculation
- CRC calculation between two addresses of the memory

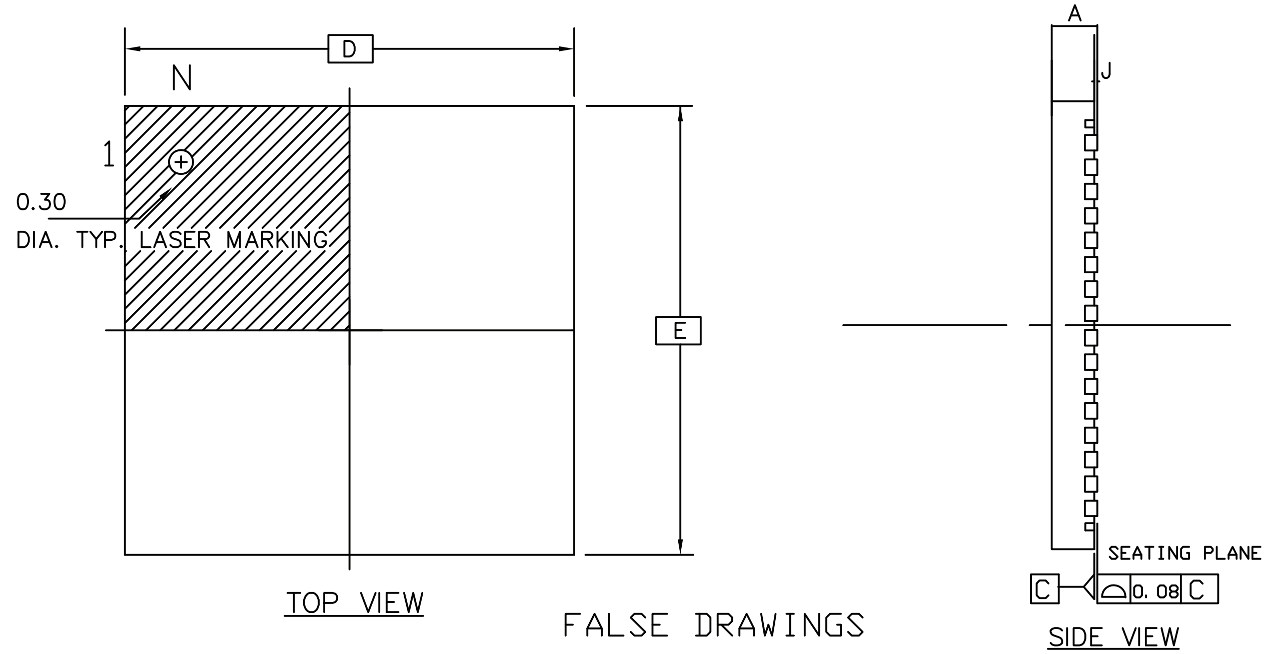
Table 13-1. 48-lead LQFP Package Dimensions (in mm)

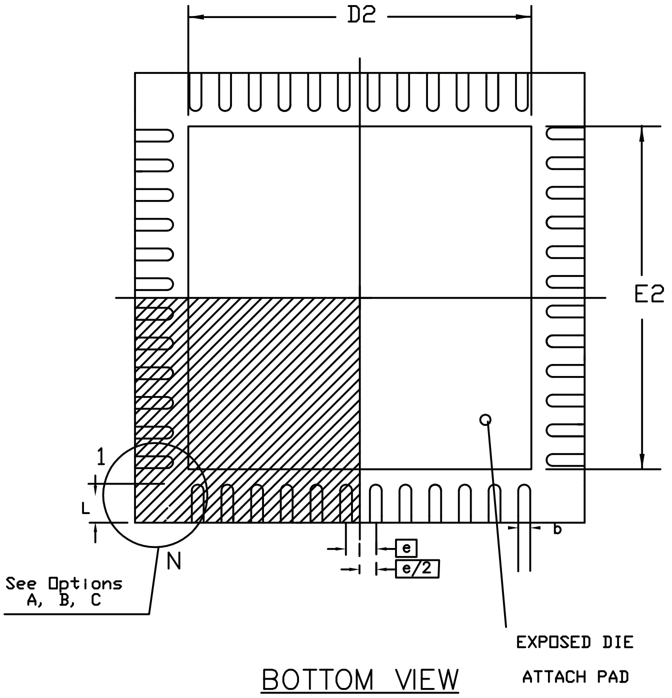
Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	9.00 BSC			0.354 BSC		
D1	7.00 BSC			0.276 BSC		
E	9.00 BSC			0.354 BSC		
E1	7.00 BSC			0.276 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	5.50			0.217		
E2	5.50			0.217		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Table 13-2. 64-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Figure 13-4. 48-pad QFN Package





COMMON DIMENSIONS IN MM

SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	0.85	0.90	
J	0.00	----	0.05	
D/E	7.00 BSC			
D2/E2	5.00	5.10	5.20	
N	48			
e	0.50 BSC			
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	

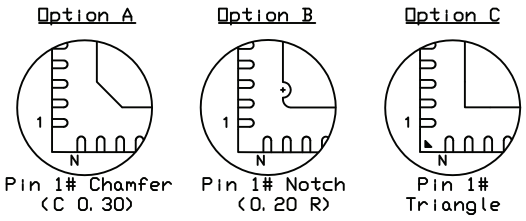
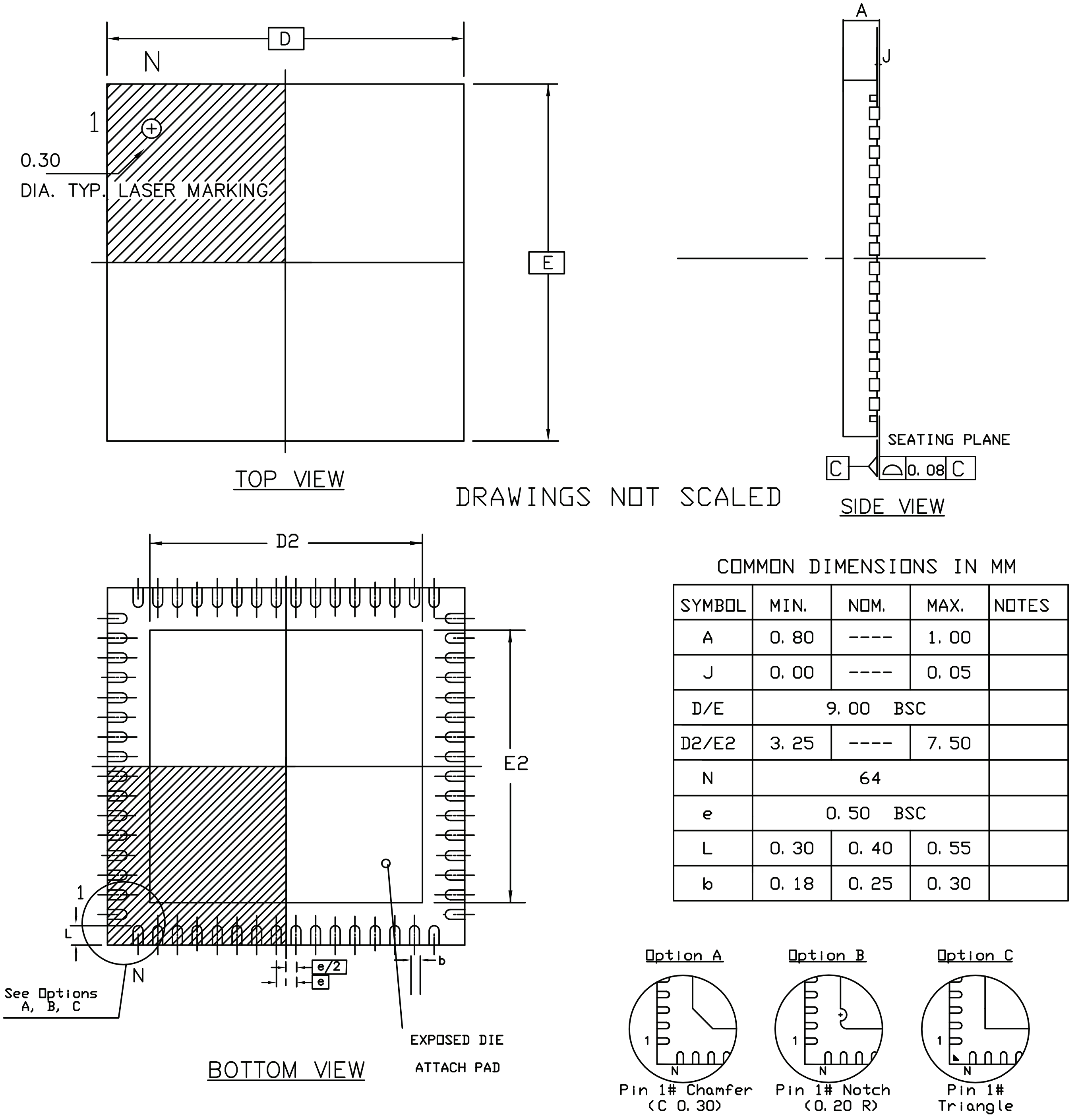


Figure 13-5. 64-pad QFN Package Drawing



COMMON DIMENSIONS IN MM

SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	----	1.00	
J	0.00	----	0.05	
D/E	9.00 BSC			
D2/E2	3.25	----	7.50	
N	64			
e	0.50 BSC			
L	0.30	0.40	0.55	
b	0.18	0.25	0.30	

Revision History

Doc. Rev	Comments	Change Request Ref.
6500CS	Missing PGMD8 to 15 added to Table 4-1, “100-lead LQFP SAM3S4/2/1C Pinout” and Table 4-2, “100-ball LFBGA SAM3S4/2/1C Pinout”. Section 5.7 “Fast Startup” updated. Typo fixed on back page: ‘techincal’ --> ‘technical’. Typos fixed in Section 1. “SAM3S Description”. Missing title added to Table 14-1. PLLA input frequency range updated in Section 10.5 “Clock Generator”. A sentence completed in Section 5.5.2 “Wait Mode”. Last sentence removed from Section 9.1.3.10 “SAM-BA® Boot”. ‘three GPNVM bits’ replaced by ‘two GPNVM bits’ in Section 9.1.3.11 “GPNVM Bits”. Leftover sentence removed from Section 4.1 “SAM3S4/2/1C Package and Pinout”.	rfo 7536 7524 7494 7492 7428 7394
6500BS	“Packages” on page 1, package size or pitch updated. Table 1-1, “Configuration Summary”, ADC column updated, footnote gives precision on reserved channel. Table 4-2, “100-ball LFBGA SAM3S4/2/1C Pinout”, pinout information is available. Figure 5-1, "Single Supply",Figure 5-2, "Core Externally Supplied" , updated notes below figures. Figure 5-2, "Core Externally Supplied", Figure 5-3, "Backup Battery", ADC, DAC, Analog Comparator supply is 2.0V-3.6V. Section 12.13 “Analog Comparator”, “Peripherals” on page 1, reference to “window function” removed. Section 9.1.3.8 “Unique Identifier”, Each device integrates its own 128-bit unique identifier.	7214 6981 7201 7243/rfo 7103 7307
6500AS	First issue	